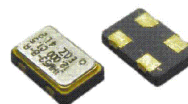


7 x 5 x 1.8mm SMD Spread Spectrum Oscillator, Low Jitter

Page 1 of 2

- Provides up to 15dB reduction in system EMI
- 'Drop-in' replacement for standard clocks
- Choice of modulation rate and spread
- Miniature package: 7.0mm x 5.0mm x 1.8mm



In electrical systems the principal cause of electro-magnetic interference (EMI) is the system clock oscillator. Traditional methods of 'patching-up' systems with too high a level of EMI is to use ferrite beads, filters, ground planes, metal shielding and similar costly methods. However, the most efficient and economic method to reduce EMI is to reduce it at source: replace the system clock oscillator with a low EMI clock oscillator.

Compared with conventional clock oscillators, Spread Spectrum (Dithered) Oscillators can reduce EMI by as much as 15dB. The part is a 'drop-in' replacement for a standard clock oscillator hence there is no requirement to re-design existing PCBs.

APPLICATIONS

- Printers, Multiple Function Printers (MPCs)
- Digital Copiers; PDAs
- Networking: LAN/WAN; Routers
- Storage Systems (CD-ROM, VCD, DVD, HDD)
- Scanners; Modems; Projectors
- Embedded Systems
- Musical Instruments
- Automotive: GPS car navigation systems
- LCD PC Monitors; LSD TVs
- ADSL; PCMCIA
- Still Digital Cameras (SDCs)

DESCRIPTION

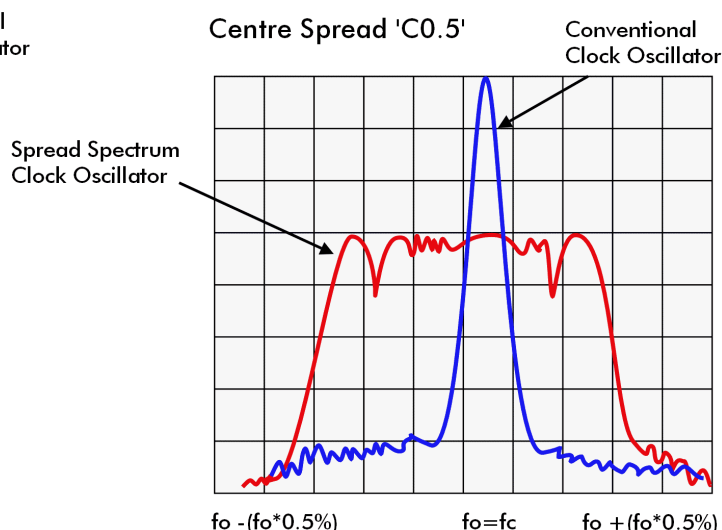
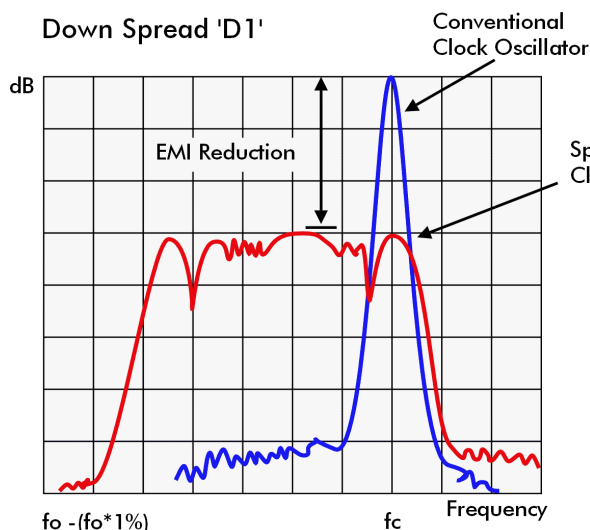
EQHM57 series low EMI oscillators can reduce system EMI by 15dB. The oscillators are a 'drop-in' replacement for standard oscillators. EMI reduction is achieved by the use of Spread Spectrum Technology whereby the mode energy is spread over a wider bandwidth. The modulation carrier frequency, operating in the kHz region, makes the process transparent to the oscillator frequency. There is a choice of modulation rates and spread to suit application requirements.

SPREAD SPECTRUM TECHNOLOGY

Unlike a conventional clock oscillator, in a Spread Spectrum Clock Oscillator the mode energy is spread over a wider bandwidth. This is achieved by the frequency modulation technique. The controlled modulation process may be applied to the 'down' side of the nominal frequency (known as **DOWN SPREAD**), or spread equally either side of nominal (**CENTRE SPREAD**). Down Spread is preferred if over-clocking would cause a problem to the system.

MODULATION TYPES - EXAMPLES

Output amplitude (dB) vs. frequency span (MHz)

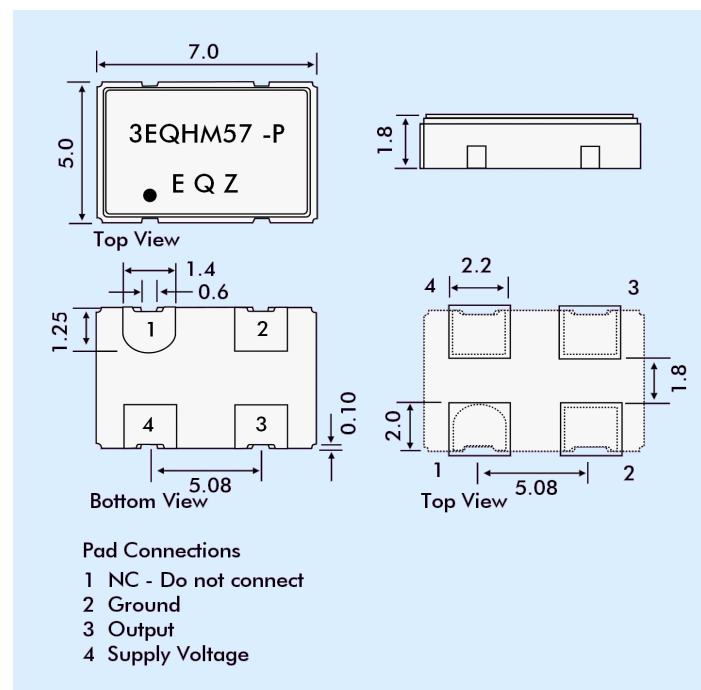


SPECIFICATION

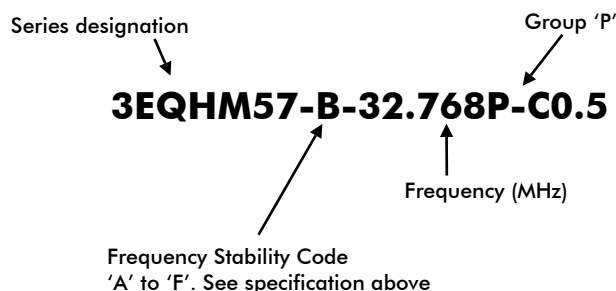
Model No:	3EQHM57 (Group 'P')
Frequency Range:	13.0MHz to 220MHz
Spread Types:	See table below
EMI Reduction*:	EMI Reduction (dB) = $10\log(\text{Total \%} \times \text{SSC Frequency (MHz)} / 0.12)$
Modulation Carrier Frequency:	25.3kHz min, 58.6kHz max. Frequency dependent Call for details
Output Logic:	CMOS
Input Voltage:	Vdd = +3.3VDC $\pm 5\%$
Frequency Stability***	Commercial (0~70°C): $\pm 25\text{ppm}$ (Spec. code = 'A') $\pm 50\text{ppm}$ (Spec. code = 'B') $\pm 100\text{ppm}$ (Spec. code = 'C')
	Industrial (-40~+85°C): $\pm 25\text{ppm}$ (Spec. code = 'D') $\pm 50\text{ppm}$ (Spec. code = 'E') $\pm 100\text{ppm}$ (Spec. code = 'F')
Output Voltage HIGH '1':	2.4V min. at 80% Vdd
Output Voltage LOW '0':	0.4V max. at 20% Vdd
Rise/fall Times:	1.2ns max, (frequency dependant)
Load:	15pF
Start-up Time:	2ms typical, 5ms max.
Current Consumption:	25mA typical, freq. dependant
Duty Cycle:	50% $\pm 5\%$ (CL=15pF, 50%Vdd)
Cycle to Cycle Jitter:	$\pm 100\text{ps}$ typ. $\pm 150\text{ps}$ max.
Output Impedance:	40 Ohms typical
Static Discharge Voltage:	>2000V (per MIL STD 833)
Storage Temperature:	-65°C to +150°C
Ageing:	$\pm 5\text{ppm}$ /year max at Ta=25°C
Packaging:	EIA 16mm tape and reel, 1k per.
Pad 1 Option:	No function available. Do not electrically connect pad 1.

Notes:

- * EMI reduction is applied to the entire frequency spectrum
dBc: with respect to no modulation. Frequency and total % spread dependant.
*** Frequency Stability parameter excludes modulation.

OUTLINE & DIMENSIONS

ENVIRONMENTAL SPECIFICATION

RoHS Compliance:	RoHS compliant and Pb (lead) free
Storage Temperature Range:	-55° to +125°C
Humidity:	85% RH, 85°C for 48 hours
Hermetic Seal:	Leak Rate 2×10^{-8} ATM-cm ³ /s max.
Solderability:	MIL-STD-2002F method 208E
Reflow:	260° for 10 seconds
Vibration:	MIL-STD-202F method 204, 35g 50Hz to 2000Hz
Shock:	MIL-STD-202F method 213B, test condition: E, 1000g $\frac{1}{2}$ sine wave

PART NUMBER CONFIGURATION


SPREAD TYPES and % MODULATION			
DOWN SPREAD		CENTRE SPREAD	
D0.5	-0.5%	C0.25	$\pm 0.25\%$
D0.75	-0.75%	C0.375	$\pm 0.375\%$
D1.25	-1.25%	C0.625	$\pm 0.625\%$
D2.0	-2.0%	C1.0	$\pm 1.0\%$
D2.5	-2.5%	C1.25	$\pm 1.25\%$
D3.0	-3.0%	C1.5	$\pm 1.5\%$
D3.5	-3.5%	C1.75	$\pm 1.75\%$
D3.75	-3.75%	C1.875	$\pm 1.875\%$